

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V_{DRM} and V_{RRM} V	Conditions
DCR960G28	2800	$T_{vj} = -40^{\circ}\text{C}$ to 125°C , $I_{DRM} = I_{RRM} = 50\text{mA}$, $V_{DRM}, V_{RRM} t_p = 10\text{ms}$, $V_{DSM} \& V_{RSM} =$ $V_{DRM} \& V_{RRM} + 100\text{V}$ respectively
DCR960G26	2600	
DCR960G24	2400	

Lower voltage grades available.

KEY PARAMETERS

V_{DRM}	2600V
$I_{T(AV)}$	960A
I_{TSM}	13000A
dV/dt^*	1500V/μs
dI/dt	500A/μs

* Higher dV/dt selections available

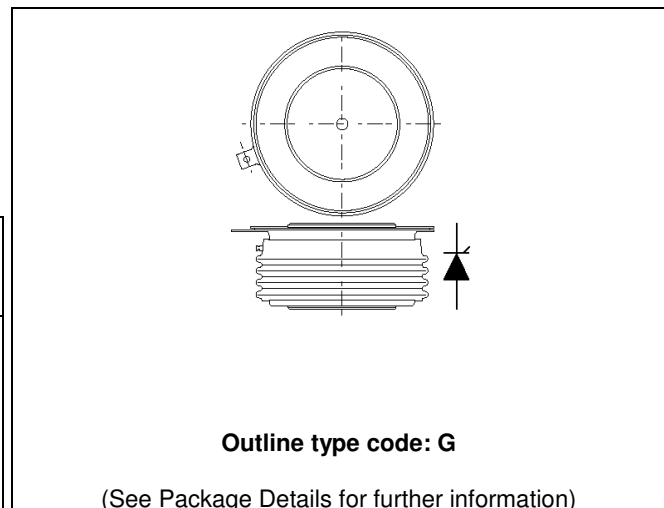


Fig. 1 Package outline

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR960G26

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

CURRENT RATINGS
 $T_{case} = 60^{\circ}\text{C}$ unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Side Cooled				
$I_{T(AV)}$	Mean on-state current	Half wave resistive load	965	A
$I_{T(RMS)}$	RMS value	-	1516	A
I_T	Continuous (direct) on-state current	-	1420	A

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I_{TSM}	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 125^{\circ}\text{C}$	13.0	kA
I^2t	I^2t for fusing	$V_R = 0$	0.845	MA^2s

THERMAL AND MECHANICAL RATINGS

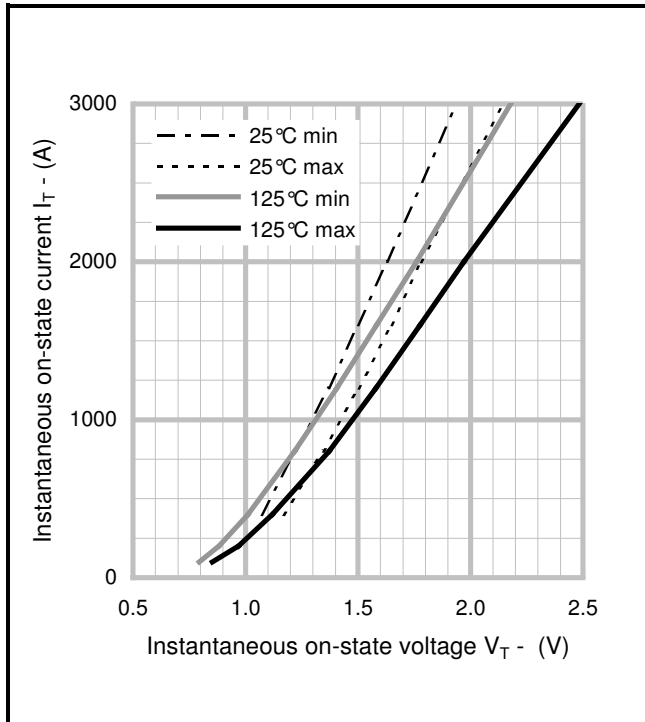
Symbol	Parameter	Test Conditions	Min.	Max.	Units	
$R_{th(j-c)}$	Thermal resistance – junction to case	Double side cooled	DC	-	0.0268	$^{\circ}\text{C/W}$
		Single side cooled	Anode DC	-	0.0527	$^{\circ}\text{C/W}$
			Cathode DC	-	0.0652	$^{\circ}\text{C/W}$
$R_{th(c-h)}$	Thermal resistance – case to heatsink	Clamping force 11.5kN (with mounting compound)	Double side	-	0.0072	$^{\circ}\text{C/W}$
			Single side	-	.0144	$^{\circ}\text{C/W}$
T_{vj}	Virtual junction temperature	On-state (conducting)	-	135	$^{\circ}\text{C}$	
		Reverse (blocking)	-	125	$^{\circ}\text{C}$	
T_{stg}	Storage temperature range		-55	125	$^{\circ}\text{C}$	
F_m	Clamping force		10	13	kN	

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min.	Max.	Units	
I_{RRM}/I_{DRM}	Peak reverse and off-state current	At V_{RRM}/V_{DRM} , $T_{case} = 125^{\circ}C$	-	50	mA	
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V_{DRM} , $T_j = 125^{\circ}C$, gate open	-	1500	V/ μs	
dl/dt	Rate of rise of on-state current	From 67% V_{DRM} to $2x I_{T(AV)}$	Repetitive 50Hz	-	250	A/ μs
		Gate source 30V, 10 Ω , $t_r < 0.5\mu s$, $T_j = 125^{\circ}C$	Non-repetitive	-	500	A/ μs
$V_{T(TO)}$	Threshold voltage – Low level	100A to 500A at $T_{case} = 125^{\circ}C$	-	0.8	V	
	Threshold voltage – High level	500A to 3000A at $T_{case} = 125^{\circ}C$	-	0.95	V	
r_T	On-state slope resistance – Low level	100A to 500A at $T_{case} = 125^{\circ}C$	-	0.7556	m Ω	
	On-state slope resistance – High level	500A to 3000A at $T_{case} = 125^{\circ}C$	-	0.51	m Ω	
t_{gd}	Delay time	$V_D = 67\% V_{DRM}$, gate source 30V, 10 Ω $t_r = 0.5\mu s$, $T_j = 25^{\circ}C$	TBD	TBD	μs	
t_q	Turn-off time	$T_j = 125^{\circ}C$, $V_R = 200V$, $dl/dt = 5A/\mu s$, $dV_{DR}/dt = 20V/\mu s$ linear	150	350	μs	
Q_S	Stored charge	$I_T = 2000A$, $T_j = 125^{\circ}C$, $dl/dt = 5A/\mu s$,	700	1500	μC	
I_L	Latching current	$T_j = 25^{\circ}C$, $V_D = 5V$	-	3	A	
I_H	Holding current	$T_j = 25^{\circ}C$, $R_{G-K} = \infty$, $I_{TM} = 500A$, $I_T = 5A$	-	300	mA	

GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	1.5	V
V_{GD}	Gate non-trigger voltage	At $V_{DRM}, T_{case} = 125^{\circ}C$	TBD	V
I_{GT}	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	250	mA
I_{GD}	Gate non-trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	TBD	mA

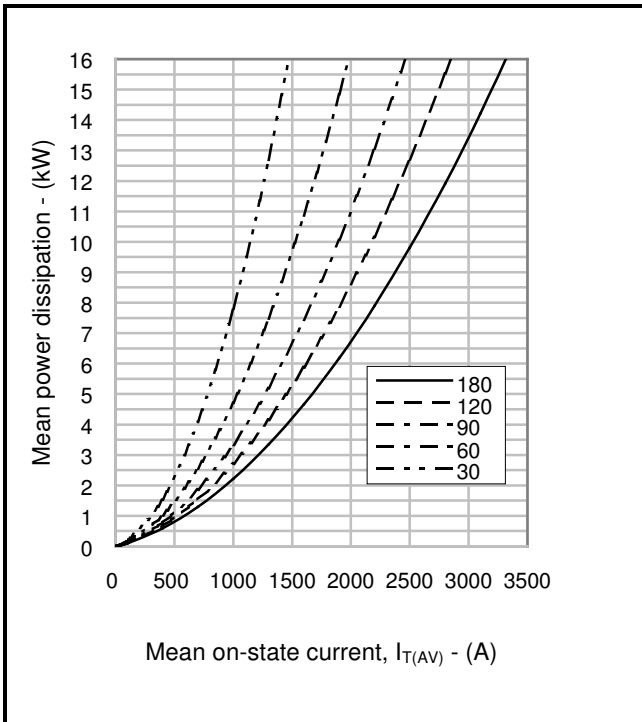
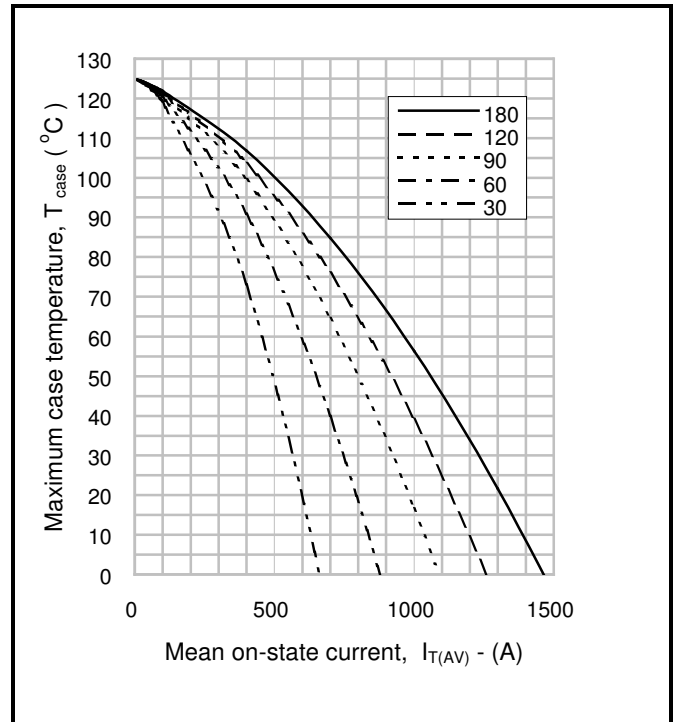
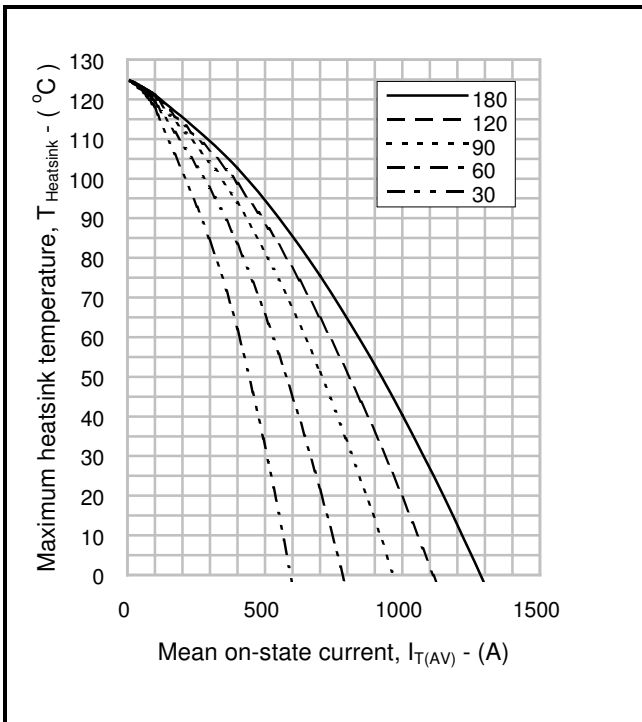
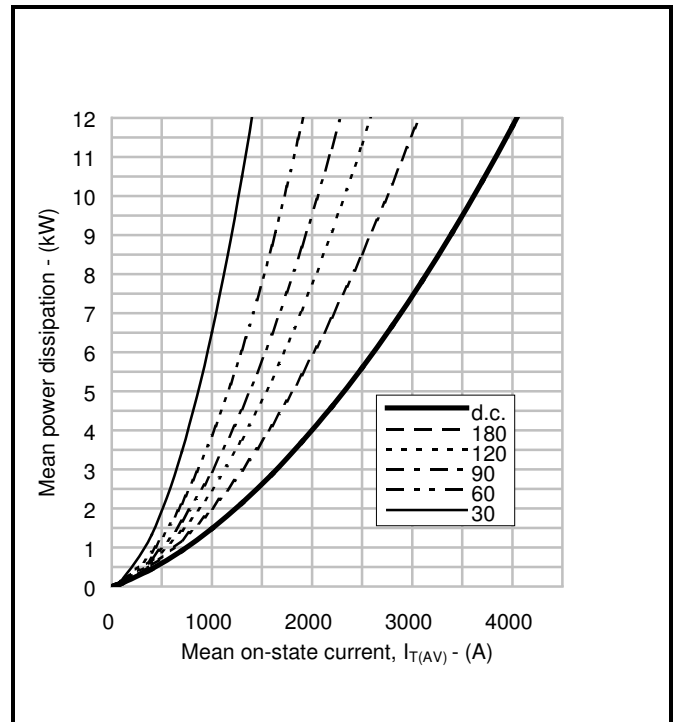
CURVES

Fig.2 Maximum & minimum on-state characteristics
 V_{TM} EQUATION

$$V_{TM} = A + B \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

Where

- A = 0.404415
- B = 0.080354
- C = 0.000415
- D = 0.003401

these values are valid for $T_j = 125^{\circ}C$ for I_T 50A to 3000A


Fig.3 On-state power dissipation – sine wave

Fig.4 Maximum permissible case temperature, double side cooled – sine wave

Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

Fig.6 On-state power dissipation – rectangular wave

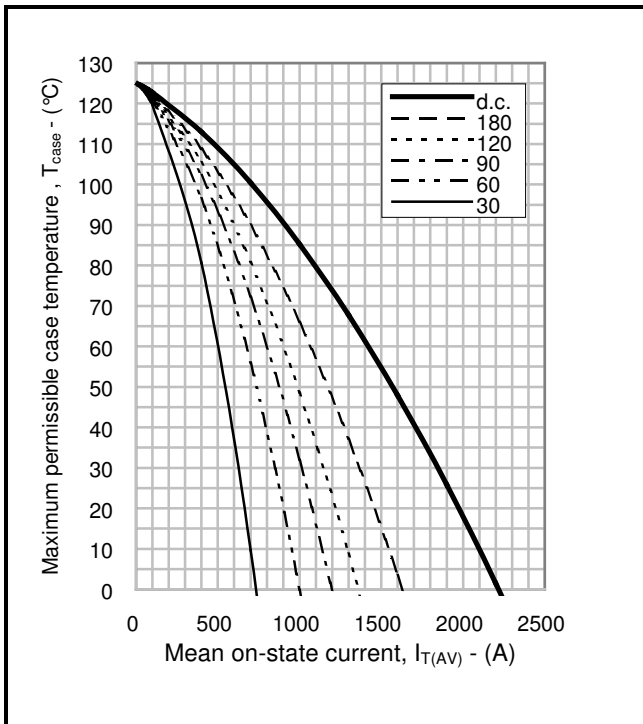


Fig.7 Maximum permissible case temperature, double side cooled – rectangular wave

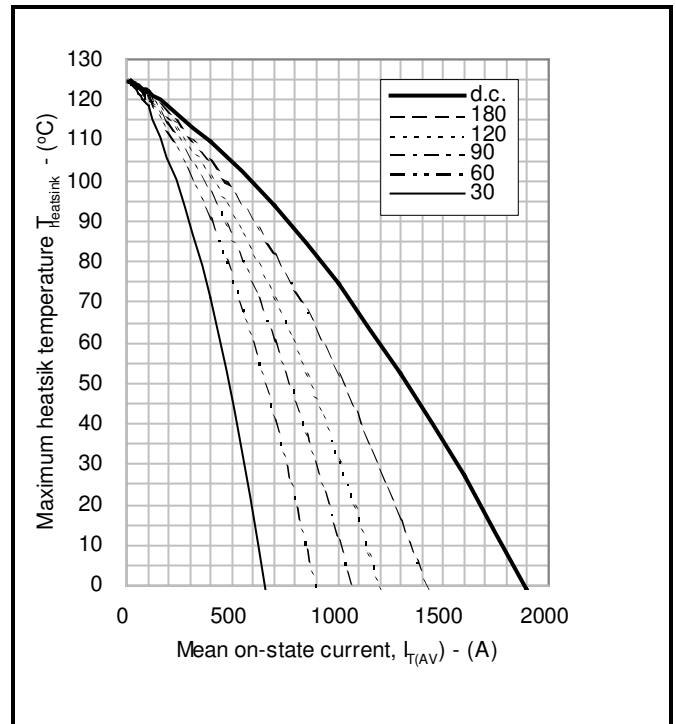


Fig.8 Maximum permissible heatsink temperature, double side cooled – rectangular wave

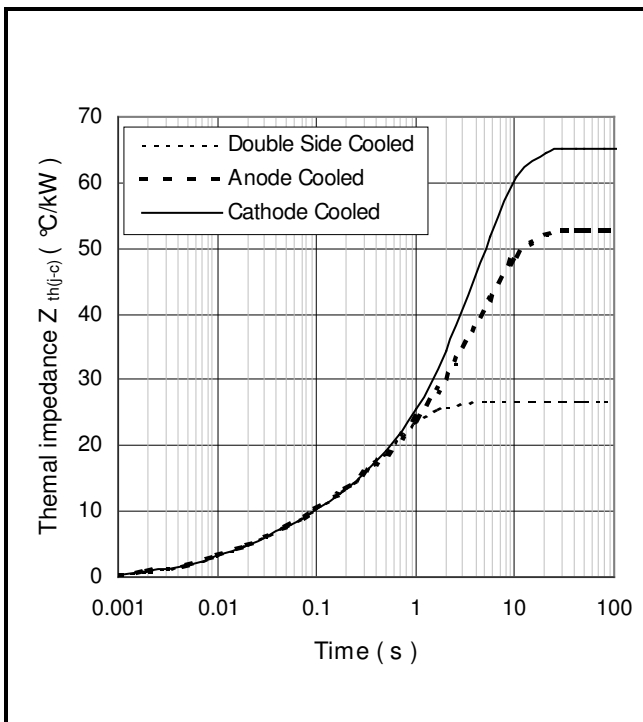


Fig.9 Maximum (limit) transient thermal impedance – junction to case (°C/kW)

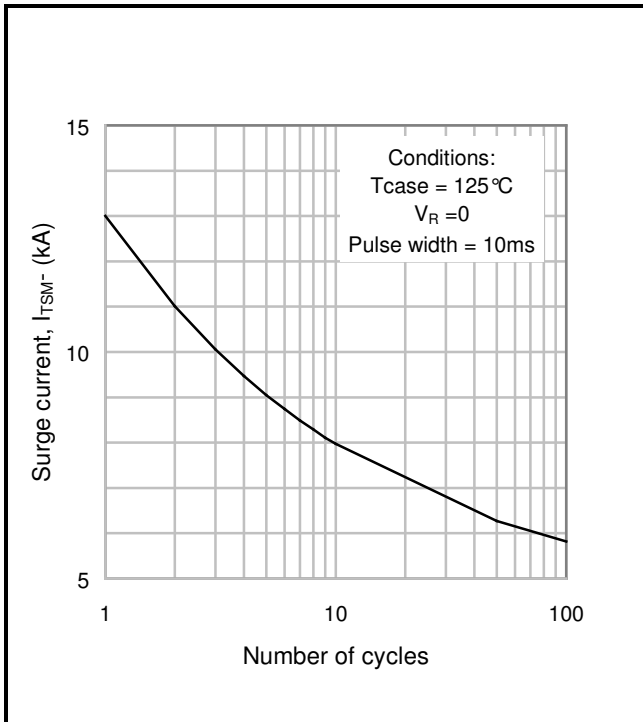
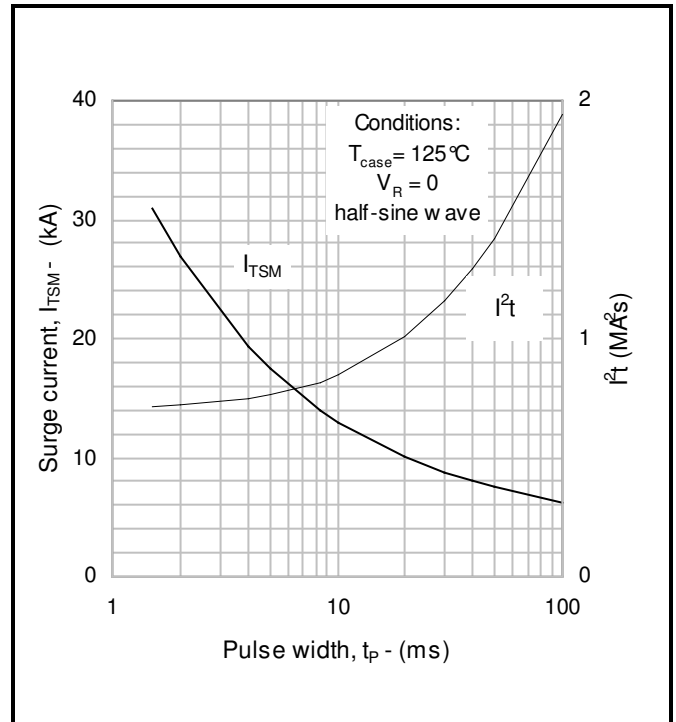
		1	2	3	4
Double side cooled	R _i (°C/kW)	2.2995	5.4226	16.9074	2.1488
	T _i (s)	0.0066401	0.0457025	0.4962482	1.8248
Anode side cooled	R _i (°C/kW)	2.3214	5.2661	10.2686	34.8031
	T _i (s)	0.0066948	0.045528	0.3484209	4.582
Cathode side cooled	R _i (°C/kW)	2.4895	5.9105	7.4256	49.3432
	T _i (s)	0.0070404	0.052895	0.3933903	4.2295

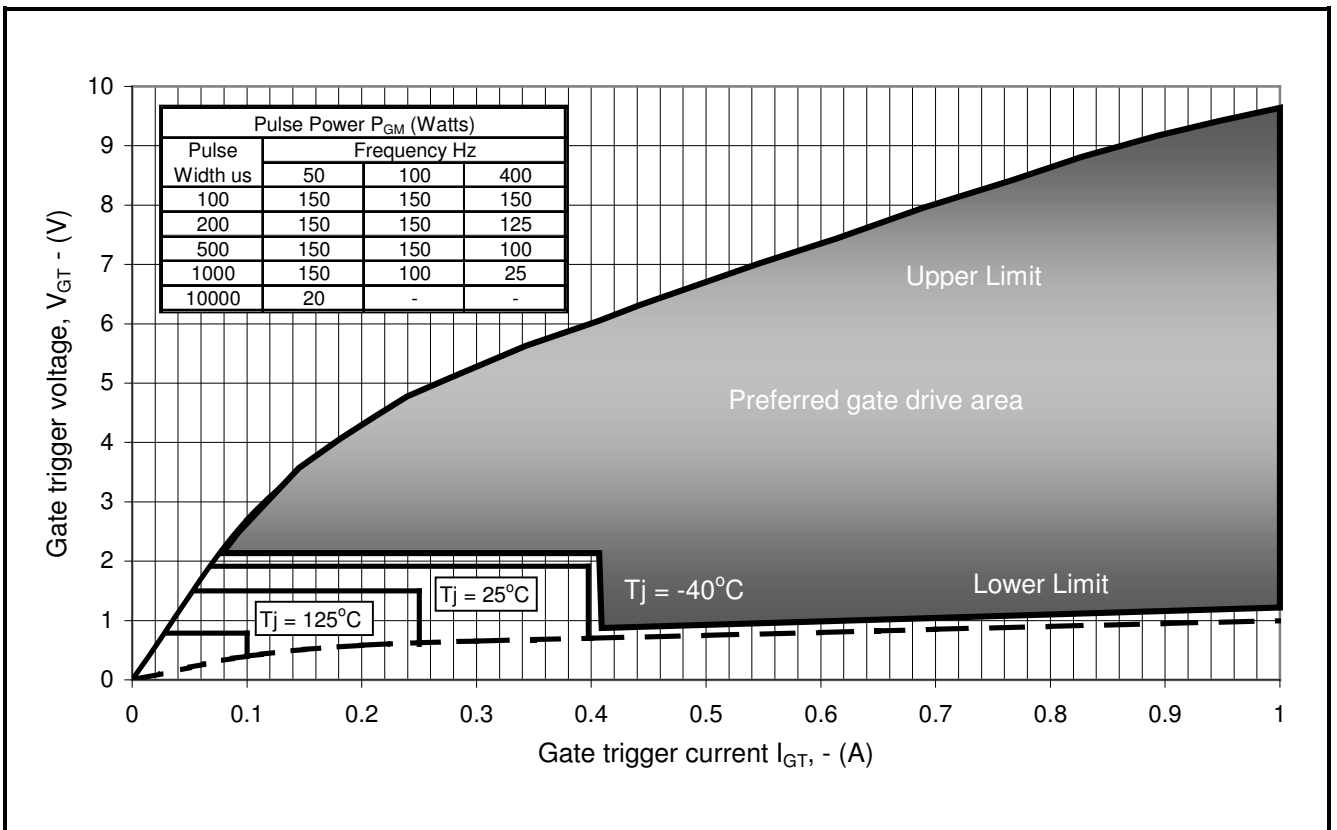
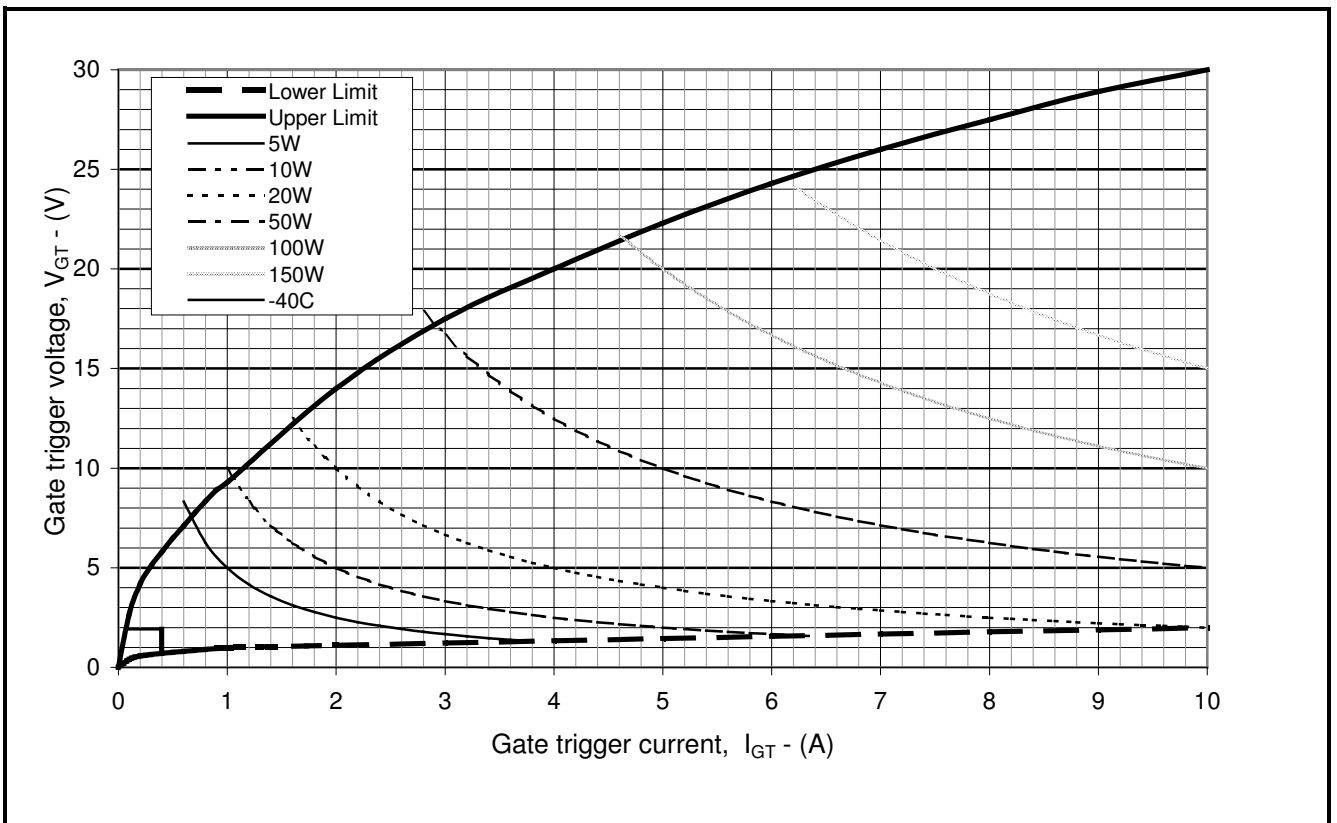
$$Z_{th} = \sum [R_i \times (1 - \exp. -(t/t_i))] \quad [1]$$

ΔR_{th(j-c)} Conduction

Tables show the increments of thermal resistance R_{th(j-c)} when the device operates at conduction angles other than d.c.

θ°	Double side cooling		Anode Side Cooling		Cathode Sided Cooling	
	sine.	rect.	sine.	rect.	sine.	rect.
180	4.15	2.72	4.15	2.72	4.13	2.71
120	4.90	4.02	4.89	4.02	4.87	4.00
90	5.74	4.79	5.73	4.78	5.69	4.76
60	6.53	5.65	6.52	5.65	6.46	5.60
30	7.16	6.64	7.15	6.62	7.07	6.56
15	7.46	7.18	7.44	7.16	7.36	7.09


Fig.10 Multi-cycle surge current

Fig.11 Single-cycle surge current


Fig12 Gate Characteristics

Fig. 13 Gate characteristics

PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

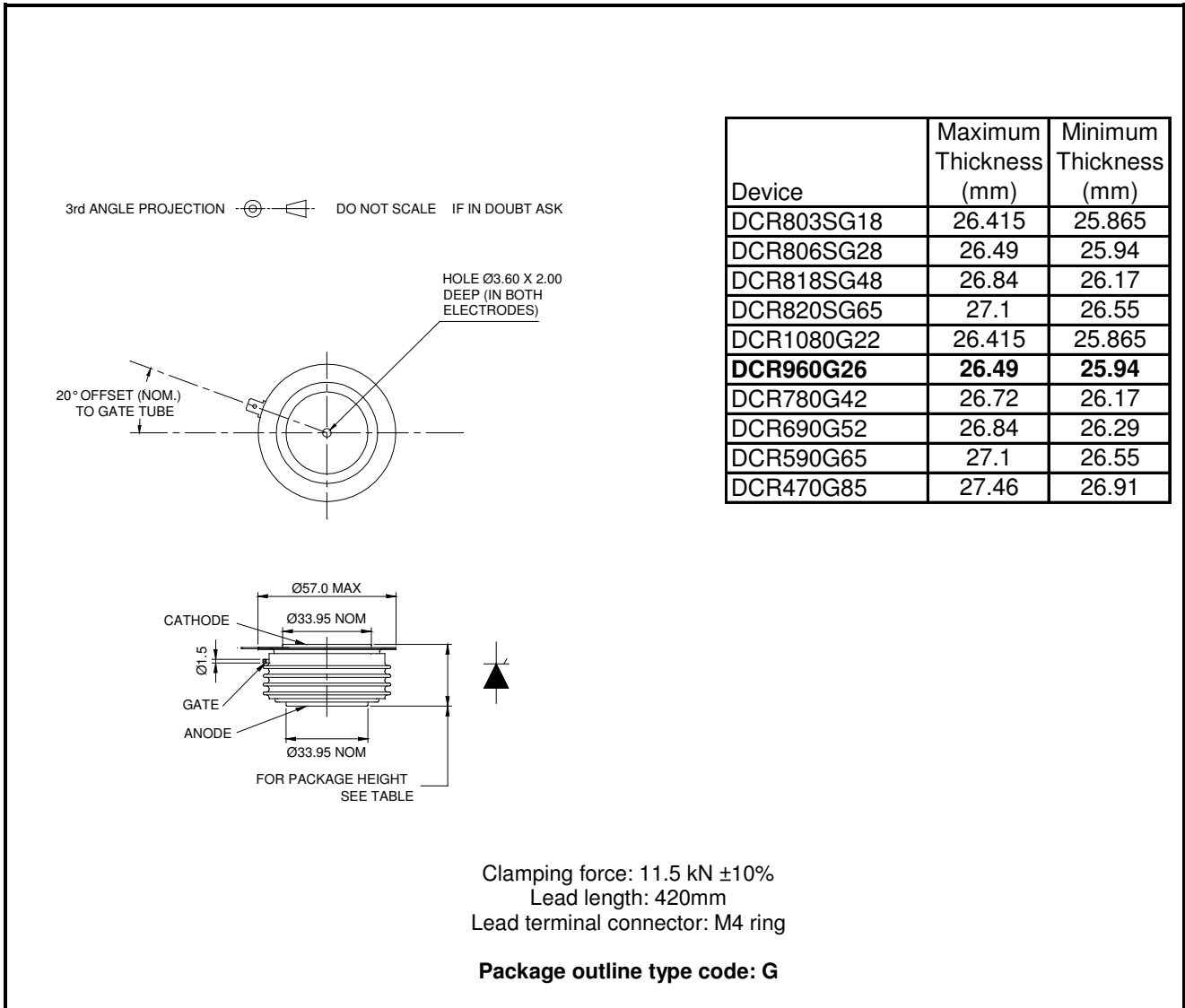


Fig.14 Package outline